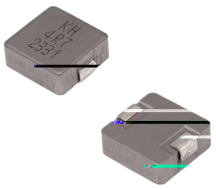
# C1 C

SMD Low Profile High Current Molded Inductor
Size 1350

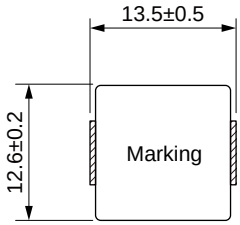


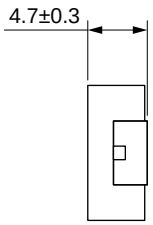
1 C

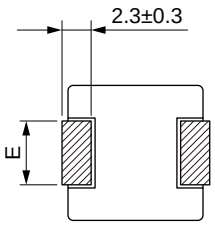
- Capable of corresponding high frequency .
- Low loss realized with low DCR.
- High performance (Isat) realized by metal dust core.
- 100% Lead(Pb)-Free and RoHS compliant.

1 1

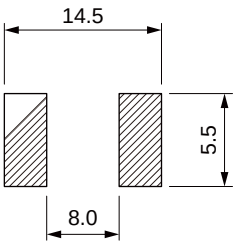
## Dimensions: [mm]



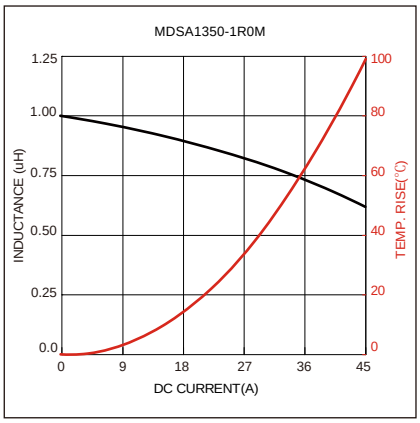

## Land Pattern: [mm]

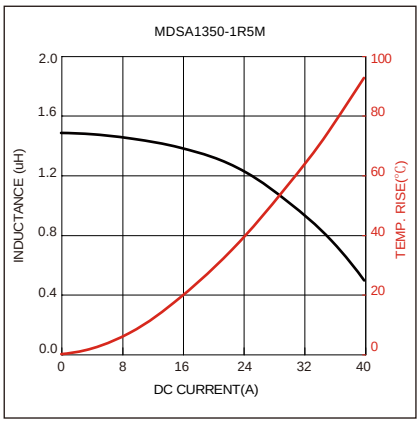


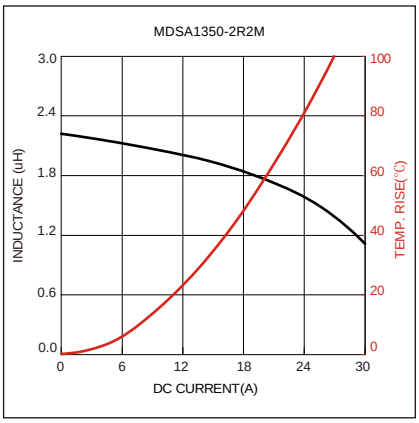

## Electrical Properties:

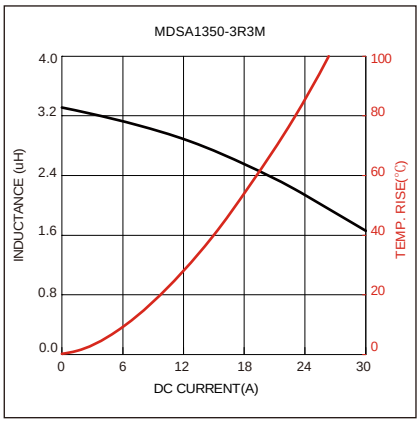
| | (µH) | | | Saturation | (mΩ) | (mΩ) | |
|---|---|---|---|---|---|---|---|
| | 0.22 | ±20% | | 64.8 | | 0.62 | 4.0±0.3 |
| | 0.47 | ±20% | 38.0 | 64.8 | 0.78 | 0.91 | 4.0±0.3 |
| | 0.68 | ±20% | 33.8 | | 1.33 | | 4.0±0.3 |
| | 1.00 | ±20% | 29.9 | 39.8 | 1.61 | 1.91 | 4.0±0.3 |
| | | ±20% | 24.9 | 30.7 | 3.22 | 3.83 | 4.7±0.3 |
| | 2.20 | ±20% | 17.0 | | 4.10 | 4.82 | 4.7±0.3 |
| | 3.30 | ±20% | | 22.8 | 6.03 | 7.00 | 4.7±0.3 |
| | 4.70 | ±20% | 13.8 | 18.4 | 8.82 | 10.2 | 4.7±0.3 |
| | 6.80 | ±20% | 11.7 | 16.3 | 13.0 | 16.0 | 4.7±0.3 |
| | 10.0 | ±20% | 10.0 | 12.8 | 19.2 | 22.2 | 4.7±0.3 |
| | | ±20% | 9.38 | 10.8 | 30.1 | 36.3 | 4.7±0.3 |

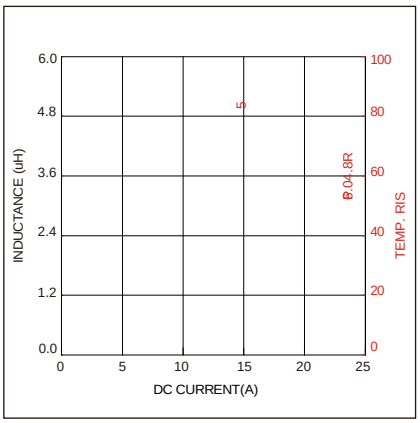
## Typical Electrical Characteristics:



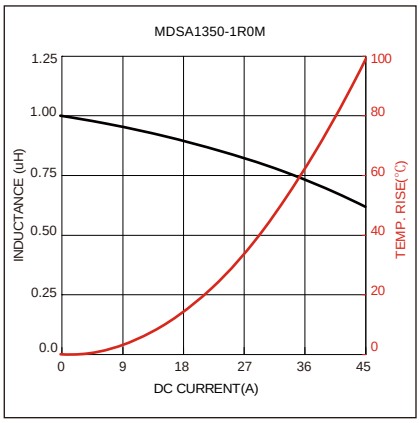



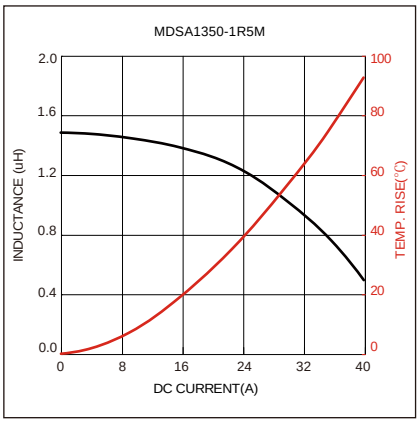



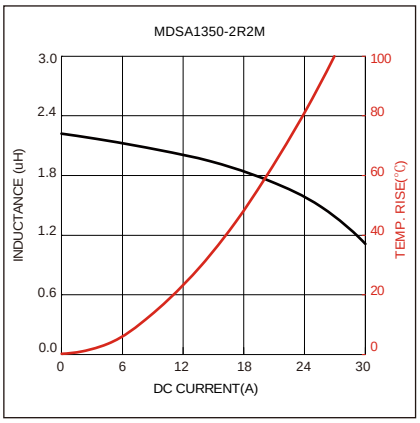



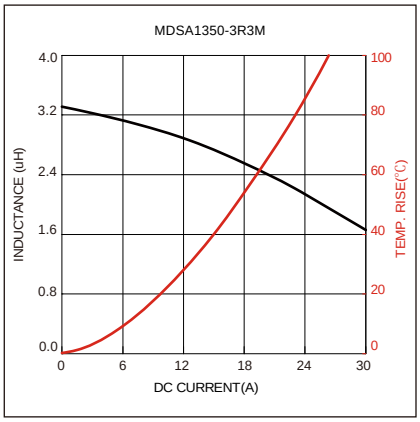



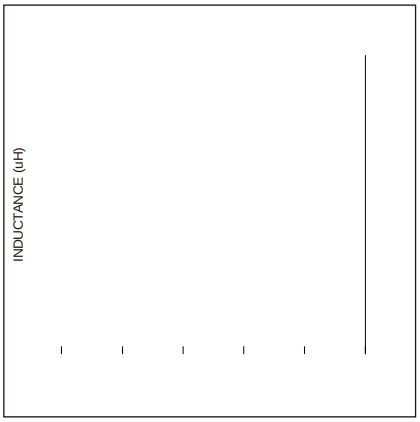
# Typical Electrical Characteristics:



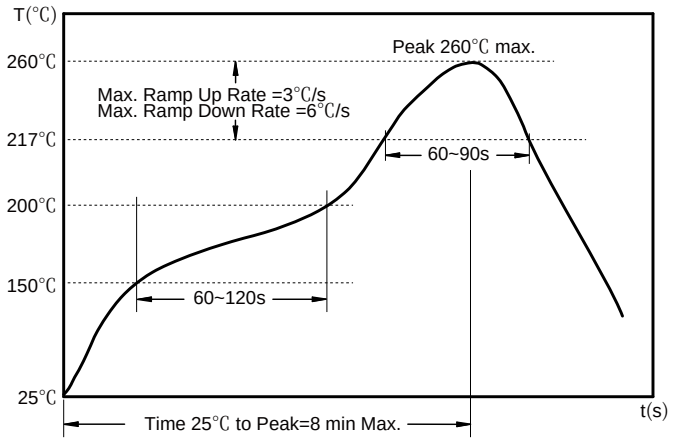



## Soldering Reflow:




Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

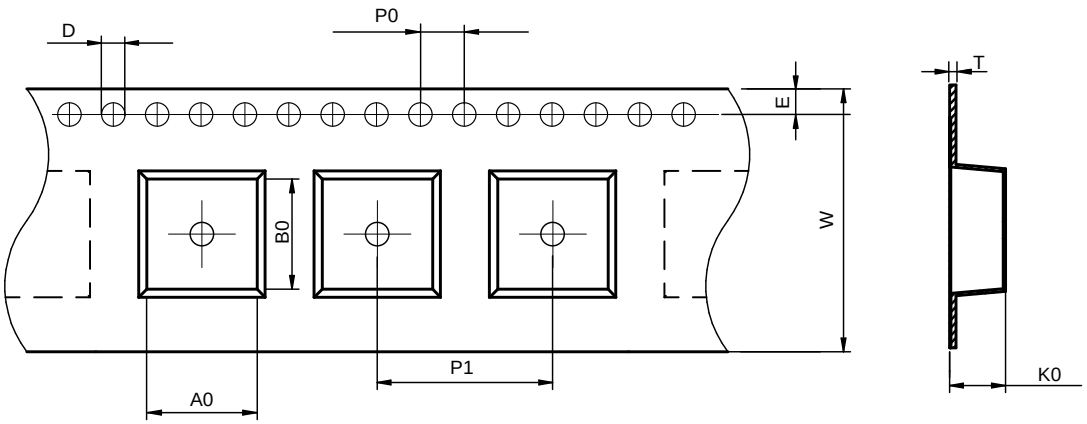
Max temperature: 260℃.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

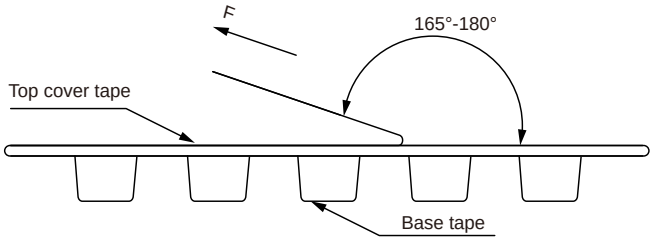
## Packaging Information:

### Tape Dimension：




| Series | A0 (mm) | B0 (mm) | D (mm) | P0 (mm) | P1 (mm) | W (mm) | K0 (mm) | E (mm) | T (mm) |
|---|---|---|---|---|---|---|---|---|---|
| MDSA1350 | 13.1 ± 0.1 | 14.0 ± 0.1 | 1.5 ± 0.1 | 4.0 ± 0.1 | 16.0 ± 0.1 | 24.0 ± 0.3 | 5.4 ± 0.1 | 1.75 ± 0.1 | 0.50 ± 0.05 |

### Peel force of top cover tape:

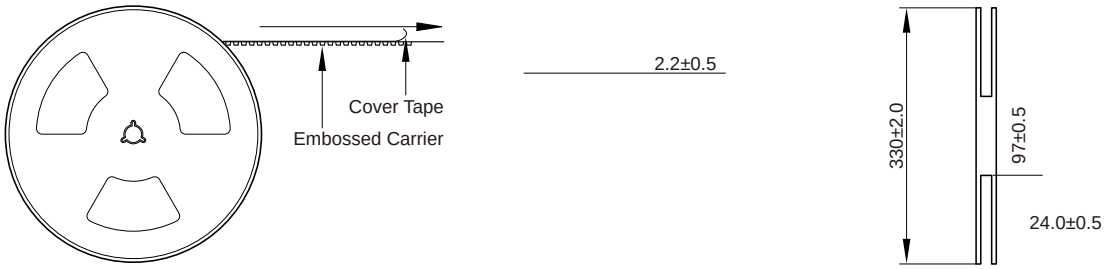



The peel force of top cover tape shall be between 0.1 to 1.3 N

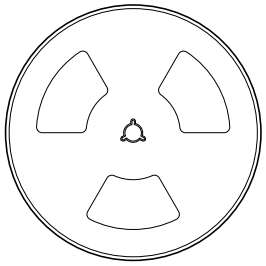
### Product Marking:

| Marking | KH+Printing Inductance+period) |
|---|---|

Reel Dimension：[mm]




Packaging Quantity:



500 Pcs/Reel

2 Reel /Inner box( 1000 Pcs)

2 Inner box/Carton box(2K Pcs)

## Cautions and Warnings:

Storage Conditions：

Operation Instructions: